

**Institute of Fundamental Studies (IFS), Kandy**

**Workshop on**

**Current Status and Future Trends in**

**Thin Film Solar PV Technology**

**28-29 June 2012**

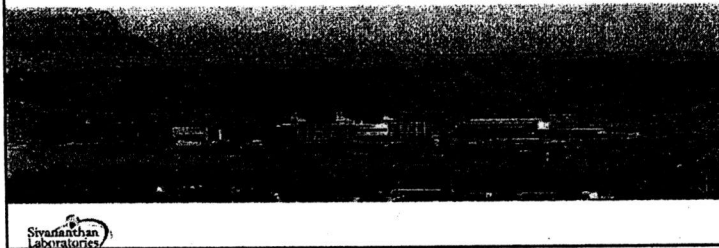
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# Global Scenario and Photovoltaics I

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## Acknowledgements

- Dr. Timothy Coutts
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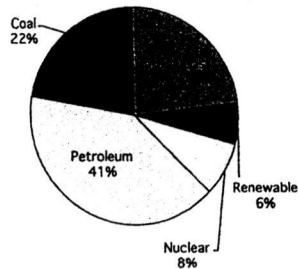
Paula Mint  
 Navigant



## US Energy 101

### Introduction

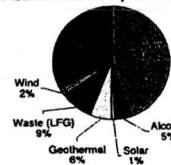
**2004 US Total Energy Consumption by Fuel Type**  
 99.6 Quadrillion BTU Energy (~100 Quads)  
 28x10<sup>12</sup> KWH  
 3.3 TW (Constant) Power  
 (2025 Projected - 133.2 Quads)



Source: 2004 Annual Energy Review  
 Energy Information Administration  
[www.eia.doe.gov](http://www.eia.doe.gov)



**2004 US Renewable Energy**  
 6.1 Quadrillion BTU (0.2 TW Power)



**2004 US Solar Energy**  
 0.063 Quadrillion BTU - 0.002 TW Power  
 (1998 91% Hot Water 6% Thermal 3% PV)

**2004 US PV Module Production**  
 ~150 MW/Year  
**2004 Cumulative World Production**  
 ~4000 MW (4 GW, 0.004 TW)



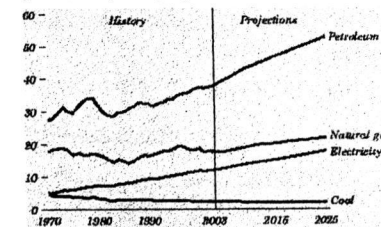
Thin-Film PV produced ~0.0003%  
 of 2004 US Energy Consumption

## US Energy 101

### Introduction

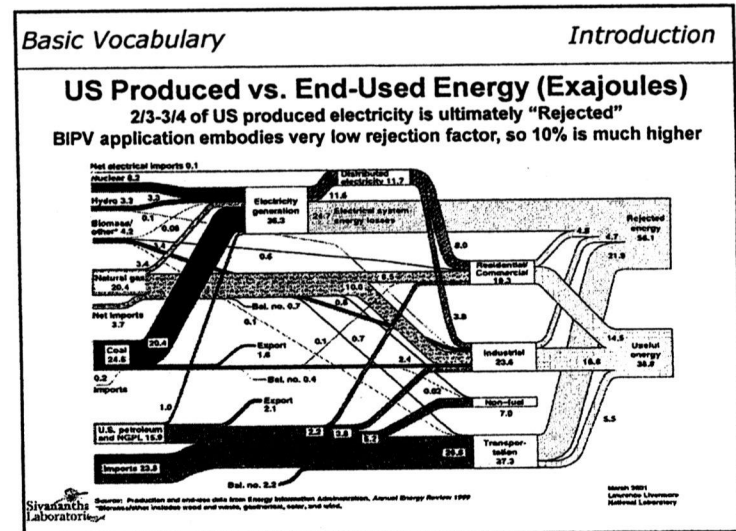
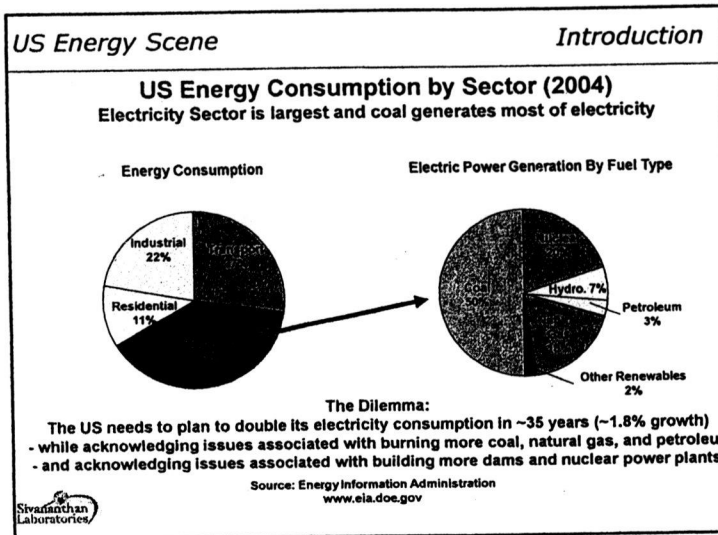
## Historical and Projected US Energy Consumption by Major Fuel Type - to 2025

Total Energy Consumption projected to increase by 1.4%/year  
 Petroleum consumption projected at 1.5%/year  
 Electricity consumption projected to increase by 1.8%/year



Source: Annual Energy Outlook 2005 - With Projections to 2025  
 Energy Information Administration  
[www.eia.doe.gov](http://www.eia.doe.gov)





**Global Energy Scenario**

Natural Gas -23%, Coal - 25%, Oil - 37%

Nuclear - 6%, Hydro - 3%, Renewable - 5%

**Projected Energy Consumption Growth by 2050:**

India - 31%, China - 146%, Middle East - 170%

**Energy Consumption Distribution:**

China - 20%, BRIC - 50%, US - 19%, ROW- 31%.

Energy Demand expected to double by 2050

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**Environmental Impact**

Percentage of CO<sub>2</sub> in ambient has increased rapidly in past 100 years.

To stabilize level we need to replace carbon based sources. Require 13000 GW of renewable energy production by 2050 i.e. 1GW/day.

Present PV production - 30 GW/year.

Big challenge and tremendous opportunity for growth:

\$ 26 to 50 Trillion Dollar Market

Requires mix of technologies - PV, CSP, Wind

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## Issues to consider for Energy Planning

- Energy Independence
- Environmental Considerations
- Renewable Energy Sources – Sustainability
- Use of local resources – Appropriate technology
- Economic Development

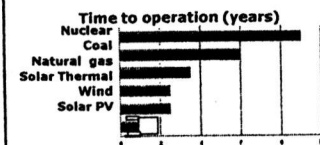


## Renewable Energy and Solar PV Overview

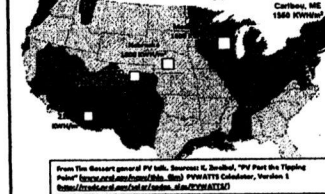
### Need For Renewable Energy

1. Meet increasing electricity demand throughout the world
2. Reduce carbon emissions and preserve water supplies
3. Reduce dependence on foreign energy
4. Provide distributed energy for developing nations

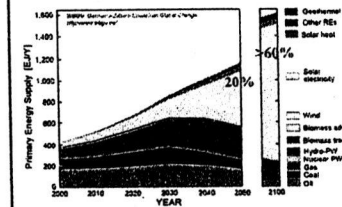
### Deployment Time



### Land Needed for Solar Energy (at 12% Efficiency)



### Long Term Solar PV Growth



## Srilankan Context

### Present Energy Mix:

- 2009 Statistics : Almost Equal use Hydropower and Thermal Power Stations for Electricity Generation.
- Great Progress in the development of Hydropower generation in last 50 years. Most of the resources already tapped.
- Future Energy Production Planning: Continue the same course (fossil fuels, coal) or consider renewable sources.



## Sustainability

### Energy Efficiency

### Minimizing Waste-

- Use of CFCs already reducing energy for lighting
- With introduction of LED further reduction.
- Not only reduces consumption, minimizes heat from wasted energy, reduces A/C cost
- Architectural design to suit climate, use of smart windows, low E TCO coated glass to minimize heat



## Renewable Energy Sources

- Biofuels – transportation needs. Use of waste organic products. E.g. ARTI in India developing simple solutions using kitchen waste.
- Wind Energy – Island nation, more options to tap for optimal use.
- Tropical Climate – Ideal for solar cells.
- Photovoltaics and Wind energy compliment each other.



## Photovoltaics

### Advantages

- Modularity – Systems can be designed at any size without paying excessive penalty.
- Deployment – Systems can be installed in months, less time than alternative choices
- Maintenance – No moving parts, minimal breakdowns.

### Disadvantage –

- Intermittent resource, need storage



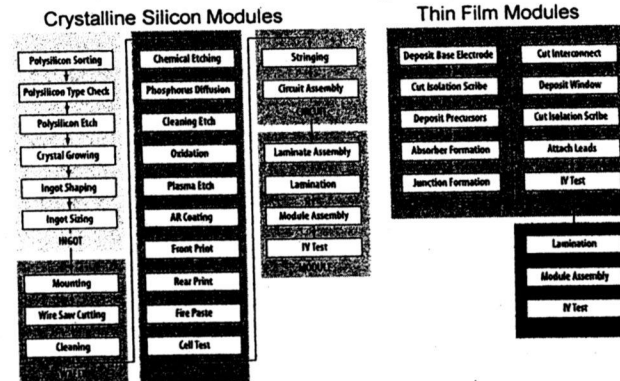
## Photovoltaics – Ideal for Srilanka

- Ideal for tropical climate
- Allows opportunity for use of highly literate population
- Reduce importation cost, energy independence and environmental benefits through reduction in greenhouse gases
- Use hydropower as storage – unique Srilankan advantage. Power on demand.
- PV and Wind complimentary sources
- Strategic Location – access to key markets



## PV Technologies- Crystalline vs Thin Film

### Module Manufacturing Sequence



## Silicon Based PV

- Most of Present PV manufacturing
- Energy intensive processing – Si production, purification, crystal growth.
- Rapid Reduction in cost in last 3 years through vertical integration
- China advantage:
  - Scaling (over 50% of world production)
  - Supply Chain Clustering
  - Large scale Government subsidies
  - Top 3 Chinese Companies project cost at \$ 0.6/W<sub>p</sub>



## Thin Film PV

- Lowest Cost production
- Room for further cost reduction through either high rate processing for CIGS and higher performance for CdTe technology
- Simplified Processing Techniques
- Lower Energy Input
- Scope for vertical integration – module to systems for total installed cost reduction



## Srilanka PV Development

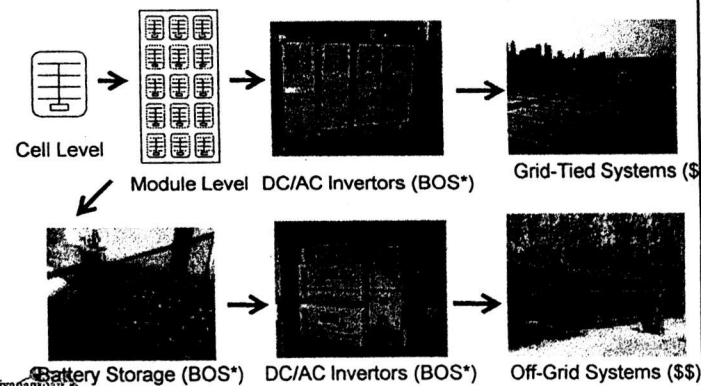
- Development of Workforce in all areas of PV
- Thin film module manufacturing – Trained workforce incentive to domestic or global manufacturers
- Coordinated effort to develop expertise from cell to system
- Use domestic market as training ground to build systems for different applications
- Cost reduction through vertical integration – Offer full solution from planning to turn-key systems
- Tap international markets – Demo functioning system under tropical conditions, Full service from building to servicing/maintaining the PV systems



## Basic Vocabulary

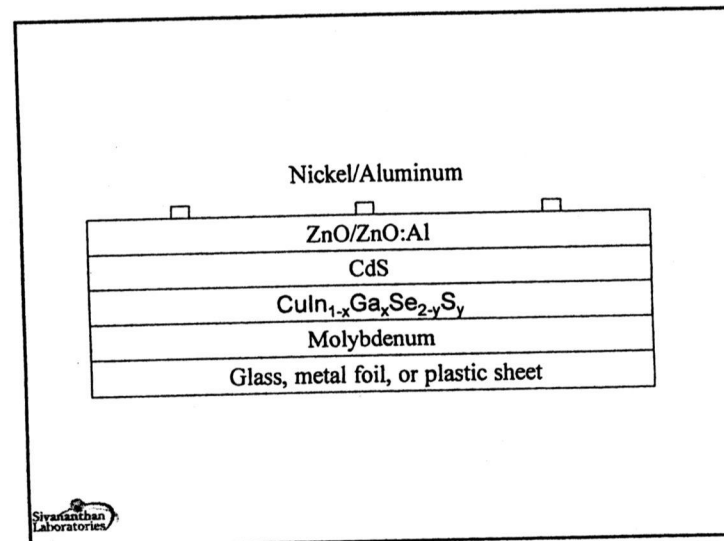
## Introduction

Cells vs. Modules vs. BOS\* (\*Balance of Systems) vs. Systems



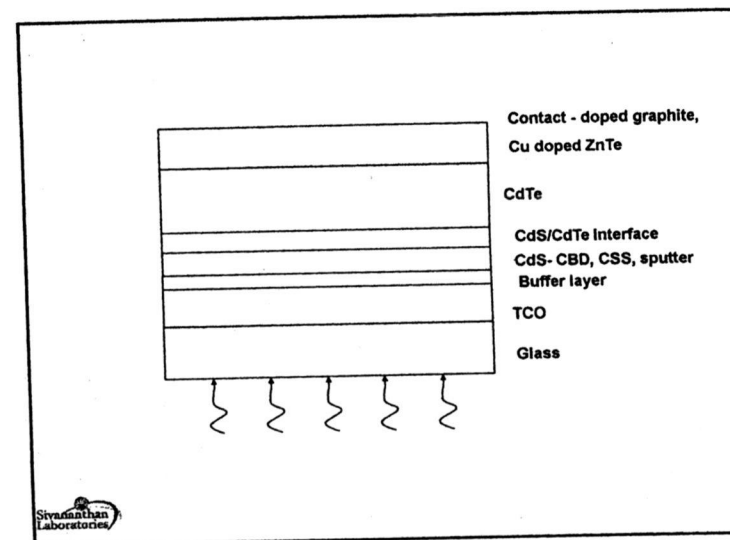
## Substrate Device Structure

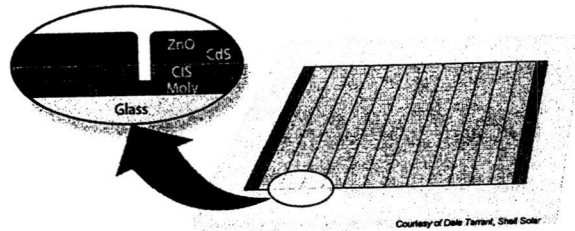
- Most commonly used. Used for CIGS, CZTS etc
- Allows freedom to chose substrates, enables flexible device architecture
- Junction formation is one of the last fabrication steps thus allows optimization of device performance
- Allows efficient use of anti-reflection coatings to minimize losses



## Superstrate structure

- Simplifies manufacturing- Glass/TCO can be sourced from vendors. Reduces capital cost .
- Optical stack with right order of refractive indices minimizes reflectance losses. No need for AR coating.
- Allows the freedom to fabricate the ohmic contact to CdTe, which is most difficult fabrication step.
- Integrated module- minimizes production cost.





Monolithic integration of TF solar cells can lead to significant manufacturing advantages; e.g., fewer processing steps, easier automation, lower consumption of materials.

DR-1

*Basic Vocabulary* *Introduction*


**Making Sense of PV Technology**  
*(What's all this about anyway?)*

**Cells vs. Modules vs. BOS vs. Systems?**

**Thin Film PV vs. Crystalline PV?**

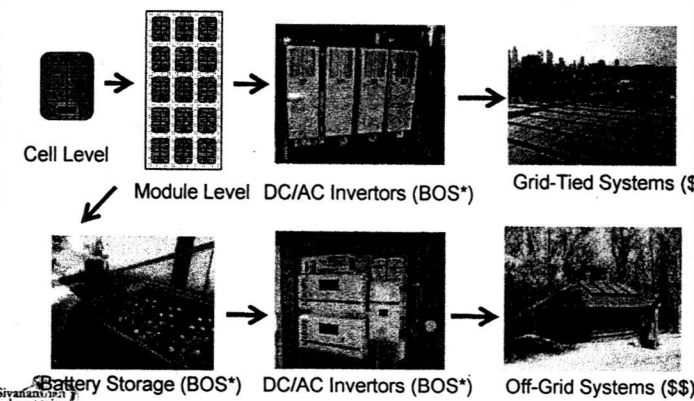
**Rigid PV vs. Flexible PV?**

**Supply-Chain Materials?**




*Basic Vocabulary* *Introduction*

**Cells vs. Modules vs. BOS\* (\*Balance of Systems) vs. Systems**



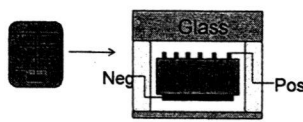
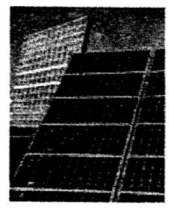
Cell Level → Module Level → DC/AC Inverters (BOS\*) → Grid-Tied Systems (\$)

Battery Storage (BOS\*) → DC/AC Inverters (BOS\*) → Off-Grid Systems (\$\$)

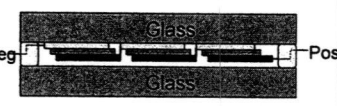
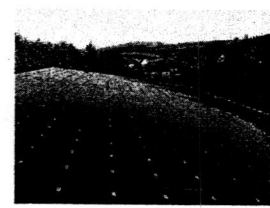



*Basic Vocabulary* *Introduction*

Crystalline PV Technology

Thin Film PV Technology

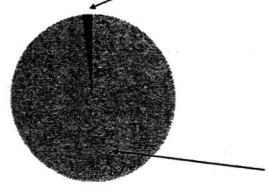






*Basic Vocabulary* *Introduction*

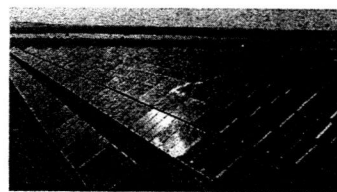
**Rigid vs. Flexible PV**

**Rigid vs. Flexible PV Markets (2004)**






2% Flexible Substrate PV



98% Rigid Substrate PV



*Basic Vocabulary* *Introduction*

### How large is the PV Roof Shingle Market?

US Residential Roof Area =  $163 \times 10^9 \text{ m}^2$   
 =  $\sim 16 \times 10^9 \text{ m}^2$   
 US Commercial Roof Area =  $50 \times 10^9 \text{ ft}^2$   
 =  $\sim 5 \times 10^9 \text{ m}^2$

**Shading Factor**  
 Residential = 78%  
 Commercial = 50%



**Roof Area Appropriate for PV**  
 US Residential =  $3.6 \times 10^9 \text{ m}^2$   
 Commercial =  $2.5 \times 10^9 \text{ m}^2$

**How much energy would this produce?**  
 Assume 1800 KWH/m<sup>2</sup>/year (US Average)  
 10% efficient PV modules

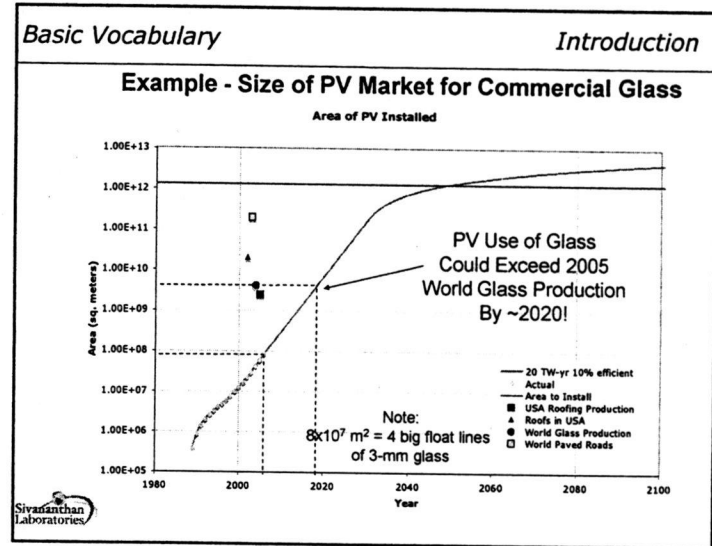
Residential + Commercial =  $1.1 \times 10^{12}$  KWH/year  
 Or 10% of U.S. Electricity Consumption in 2004

Amount of peak module power  $\sim 6 \times 10^{11}$  Watts  
 - 240 times the 2006 World Production of PV!!

**Note:**  
 BIPV market alone is 240X more pie - not just 240X the 2% piece!

Source for Roof Areas and Shading Factors: Ron Judkoff, Director Buildings and Thermal Systems, NREL



*Basic Vocabulary* *Introduction*

### Some Thin-Film CIGS, CdTe, and a-Si PV Companies

(Black - Rigid, Red - Flexible, Blue - Multiple/Undecided)

Shell Solar, CA	<b>CIS</b>	Würth Solar, Germany
Global Solar Energy, AZ		SULFURCELL, Germany
Energy Photovoltaics, NJ		CIS Solartechnik, Germany
ISET, CA		Solarion, Germany
Ascent (ITN/ES), CO		Solibro, Sweden
NanoSolar Inc., CA		CISEL, France
DayStar Technologies, NY/CA		Showa Shell, Japan
MiaSole, CA		Honda, Japan
HelioVolt, Tx		
Solyndra, CA		
SoloPower, CA		
First Solar, OH	<b>CdTe</b>	CANRON, NY (and Canada)
Solar Fields, OH/Calyxo (Germany)		Solexant, CA
AVA TECH, CO		Antec Solar, Germany
Primestar Solar, CO		Arendi, Italy
WK Solar Group, OH		Advanced Solar Power, China
Uni-Solar, MI	<b>a-Si</b>	Mitsubishi Heavy Ind. - Japan
EPV - MA		Kaneka - Japan
Iowa Thin Films, IA		

Source: Sivanathan Laboratories

*Environmental Discussion for Thin Film PV*

### Energy Balance

#### You're going to use more energy making PV than you'll generate!

- Slow PV Growth – Historical View
  - A PV module must make more energy than it took to make the module
- High PV Growth – What we have now
  - The generating capacity of all the installed arrays must exceed that used to manufacture more arrays in the next time interval
  - The "Energy Pay Back Time" (EPBT) must be less than the production doubling time (DT). Otherwise PV manufacture will be a net consumer of energy
- High PV Growth and High Net Energy Production
  - The EPBT must be significantly less than the DT. Otherwise PV will not produce the new electricity needed in the next 35 years (~40 Quads)

DB-3

*Environmental Discussion for Thin Film PV*

### Energy Balance

**Energy Payback Time (EPBT) Considers Energy Consumed During:**

- Extracting, refining, and purifying raw materials
- Production, associated materials, and transportation of modules
- Installation, balance of systems (BOS) components, and use of modules
- Module disposal or recycling

	Ribbon Si	Poly Si	Mono Si	Thin Films		
				a-Si	CIS	CdTe
Modeled Efficiency	11.5% <sup>1</sup>	13.2% <sup>1</sup> 14.0% <sup>3</sup>	14.0% <sup>1</sup>	6% <sup>2</sup>	10% <sup>3</sup>	9% <sup>1</sup> 8% <sup>3</sup>
EPBT (Years) <sup>1</sup>	1.7	2.2	2.7	-	-	1.1
EPBT (Years) <sup>2</sup>	-	2.1-3.7	-	1.1-3.0	-	-
EPBT (Years) <sup>3</sup>		5			2.5	1.7

1. V. Fthenakis and H. Kim, Proc. 2006 European MRS Meeting, Nice France (6/06)  
 2. PV FAQs, U.S. Dept. Energy Pub. No. DOE/GO-102004-2040 (and internal references, 12/04).  
 3. M. Raugle et al., 20th European PVSC, Barcelona, Spain (6/05)

Ref 1&3: www.nrel.gov/nrcpv/thin\_film/publications\_news  
 Ref 2: www.nrel.gov/nrcpv

*Minerals Availability for Thin Film PV*

### Energy Balance

## So what are the actual payback times?

Technology	EPBT (Years)
Multi-Si 13.2% roof-top, European production	2.2
CdTe 8% roof-top, European production	1.0
CdTe 9% ground-mount, U.S. production	1.1

V. Fthenakis and E. Alsema, PIP 14, 275-280, 2006

*Minerals Availability for Thin Film PV*

### Overview

## Mineral Resource Considerations for Thin Films

(Si, a-Si, CuInGaSe<sub>2</sub>, CdTe)

Technology	Material	World Production <sup>a</sup>	Minerals Required <sup>b</sup>	% of Current Production	Annual Growth Needed (%)
Crystalline silicon	Purified silicon	25,000 MT/yr <sup>b</sup>	130,000 MT	520%	3.7% <sup>c</sup>
	Silver (grid/cell paste)	20,000 MT/yr	6,000 MT	30%	0.52% <sup>d</sup>
Thin-film Cu (In, Ga) Se <sub>2</sub> alloys	Indium	250 MT/yr (byproduct)	400 MT	160%	2.0% <sup>e</sup>
	Selenium	2,200 MT/yr	800 MT	36%	0.6% <sup>f</sup>
	Gallium	180 MT/yr	70 MT	47%	0.9% <sup>g</sup>
Thin-film cadmium telluride	Tellurium	450 MT/yr (2,000 unused byproduct)	933 MT	38% (of total, including unused)	2.2%
	Cadmium	26,000 MT/yr (byproduct)	800 MT	3%	0.06% <sup>h</sup>
Thin-film silicon	Germanium	270 MT/yr (3,200 unused byproduct)	40 MT	1% (of total, including unused)	0.7%

<sup>a</sup>Necessary production for each type of PV technology to produce 20 GW/yr by 2050.  
<sup>b</sup>Metric Tons.  
<sup>c</sup>Elemental silicon is not constrained by supply; current production is low because of low demand.  
<sup>d</sup>Indium is a byproduct of zinc, which has been growing at 3%/yr for 50 years. Indium growth will probably exceed demand because of growth in zinc production. Indium production would only have to increase 2%/yr to keep pace with demand.  
<sup>e</sup>Selenium is a byproduct of copper; an increase of only 0.16%/yr would keep pace with demand.  
<sup>f</sup>Gallium is not constrained by supply; current production is low because of low demand.

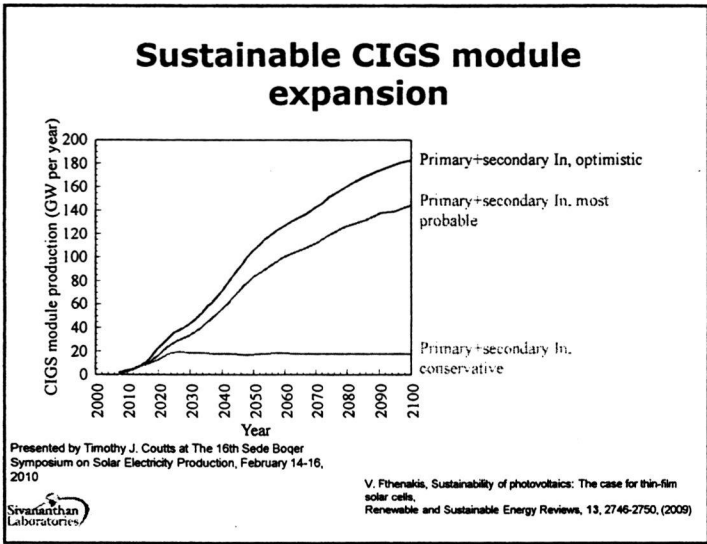
Source: PV FAQs, DOE/GO-102004-1834 (1/04), www.nrel.gov/nrcpv

*Environmental Discussion for Thin Film PV*

### Overview

## Sustainable CdTe module expansion

V. Fthenakis, Sustainability of photovoltaics: The case for thin-film solar cells, Renewable and Sustainable Energy Reviews, 13, 2746-2750, (2009)

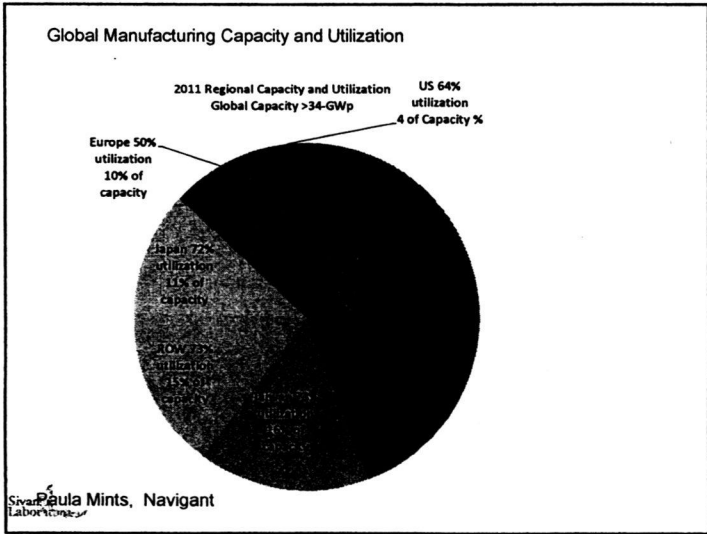


*Environmental Discussion for Thin Film PV*

### Overview

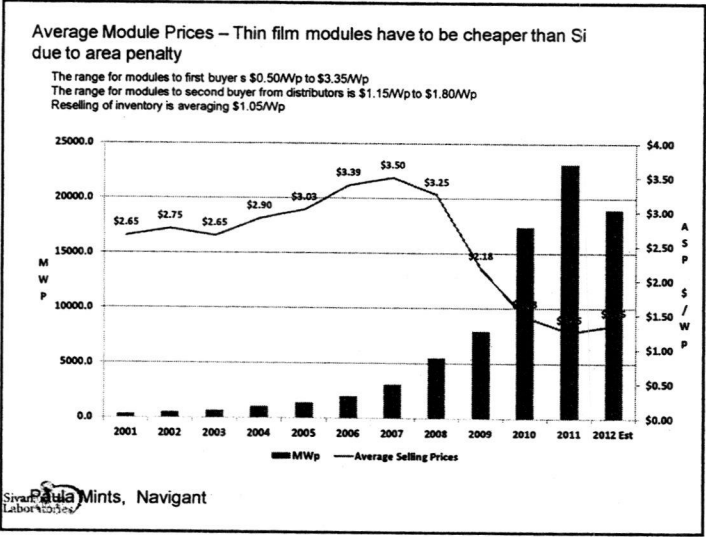
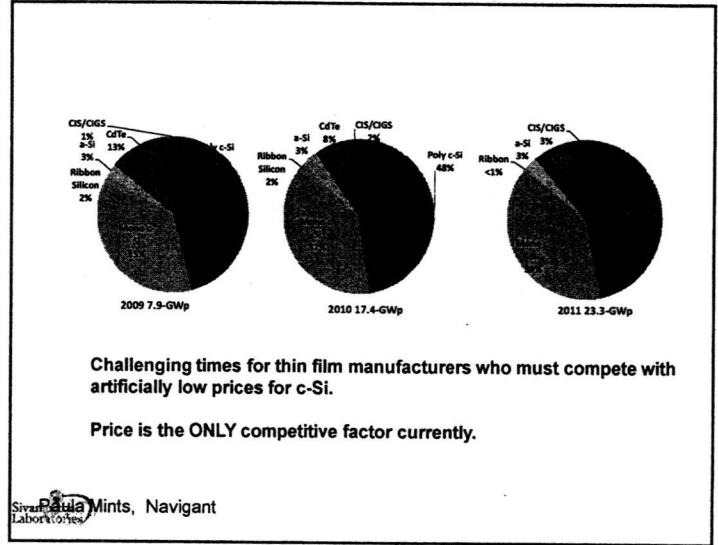
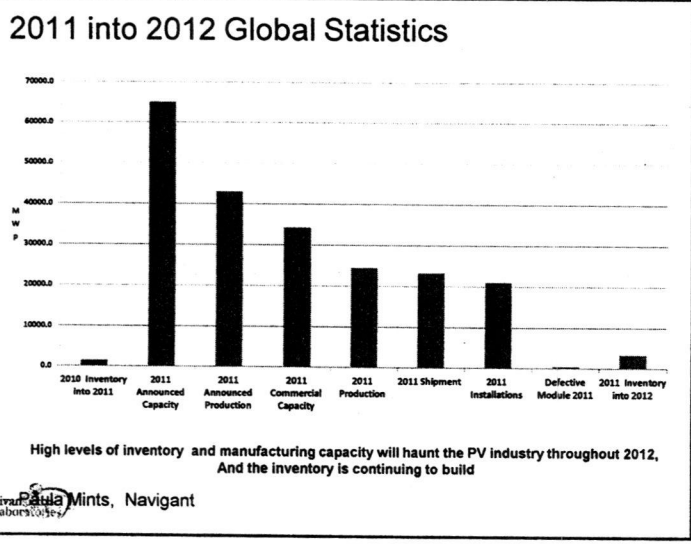
#### Summary Comments on Minerals Availability

- The supply of tellurium (and indium) has been dictated by demand, not availability
- The level of understanding of these "mineral streams" is not as high as other minerals that have had a longer demand history
  - We are not very far up "Hubbert's Curve" on these commodities
- New/Alternative directions:
  - In - This group III element could be replaced by II-IV combinations such as Zn:Sn to form a different quaternary alloys (Kesterites =  $Cu(Zn_xSn_{1-x})Se_2$  or  $Cu(Zn_xSn_{1-x})S_2$ )
  - Te - In addition to Zn ores, Te appears to associated also with volcanic activity, which suggests a new sources entirely



### Present status

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## Future Projections

Siva Prasad Mints, Navigant  
Laboratories

### Cost Projections

C- Si - at present \$1.25-1.50/W<sub>p</sub>

Projected to go down to \$0.60/W<sub>p</sub>

For further cost reduction to \$ 1/W<sub>p</sub> for system cost, need to reduce production cost and improve performance for all technologies.

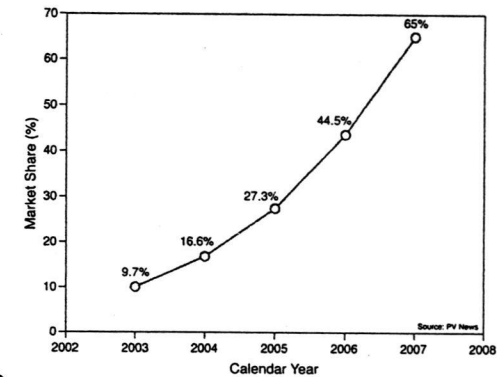
- Si - Poly Si, Thin Si, HIT cells.
- III-V - Multi-junction, concentrators.
- Thin films - a-Si, Polycrystalline thin films



### Why is Thin-Film PV Important?

Introduction

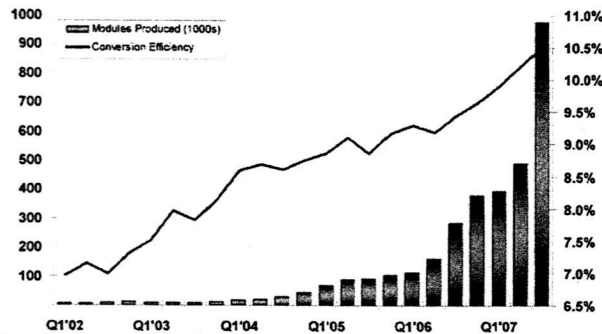
#### Thin Film PV Market Share - USA



### Why is Thin-Film PV Important?

Introduction

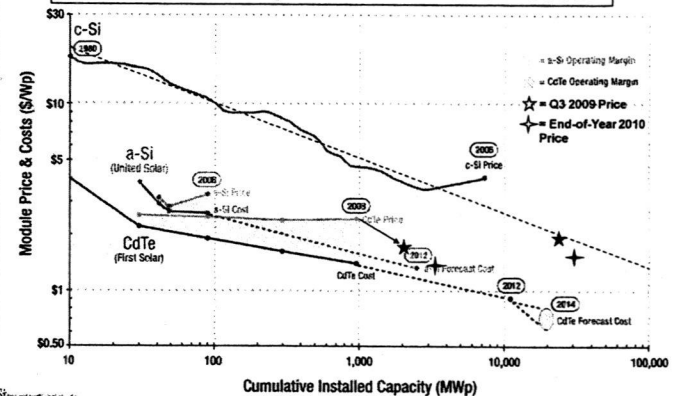
#### Conversion Efficiencies & Module Shipments

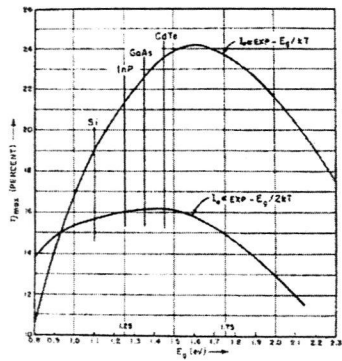


### Why is Thin-Film PV Important?

Introduction

#### How Much Does/Will Thin-Film PV Cost?





Efficiency vs band gap for different A values



Overview

### Conclusions

- Significant potential exists for new Thin film PV products to improve performance and reduce cost
- Thin-film products will compete in different segments
  - Flexible products for niche BIPV
  - Rigid products for utility scale
- Issues include:
  - Reducing EPBT further (<< 6 months?)
  - Increasing reproducible cell efficiency to 20% or greater
  - Keeping ahead of competing technologies in cost
- The rapid market penetration is forcing answers to questions few people have asked or even understand!
  - Will cost of Te remain high so that module recycling is profitable?

1-1

## Electrical Properties

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### Overview

### Thin-Film Technologies

## Why Thin-Film PV?

Average Need US Home - 5 kW<sub>p</sub>  
 Present grid-tied PV system price - \$3-4/W<sub>p</sub> (with tax incentives)  
 PV system ~\$15K-\$20K  
 Utility cost - \$1000/year, cost balance in 15-20 years  
 Need to reduce cost to \$ 1/W<sub>p</sub> (= \$0.5 for PV module + \$0.5 BOS)

c-Si - ~\$1/W<sub>p</sub> (Present Cost and Price)  
 Projected to go down to <\$0.7/W<sub>p</sub>  
 Need Modules at \$0.5/W<sub>p</sub> (Price)  
 Reduce production cost and/or improve performance

- Si - Poly Si, Thin Si
- III-V - Multi-junction, concentrators
- Thin films - a-Si, Polycrystalline thin films



### Overview

### Thin-Film Technologies

## Crystalline vs. Thin Film PV

### Crystalline PV Technologies

- Lattice-matched substrates, slow growth, thermal equilibrium.  
Very few defects = high performance
- \$/Watt = Expensive Process/Higher Performance

### Thin-Film PV Technologies

- Economic considerations dominate
- High throughput, inexpensive substrates
- Produces lots of defects that limit device performance
- \$/Watt = Cheaper Process/Lower Performance

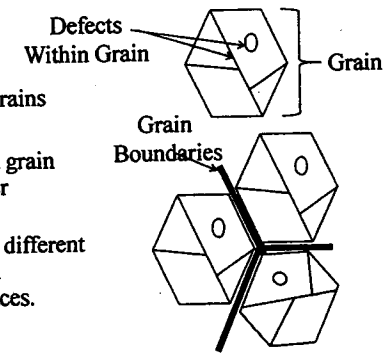


### Overview

### Thin-Film Technologies

## Issues to Consider in Thin-Film PV

- Substrates
- Grains
  - Defects within the grains
- Grain Boundaries
  - Electrical activity at grain boundaries and other structural defects.
- Interaction between the different layers of the device and properties of the interfaces.



*Overview* *Thin-Film Technologies*

## Substrates for Thin Film Growth

Some Considerations:

- Softening Point
- Thermal coefficient of Expansion
- Out Diffusion
- Cleaning

Glass type	Coeff. of Thermal Exp	Softening point (C)	Strain Point (C)
Sodalime	$9.35 \times 10^{-6}/C$	696	473
Borosilicate	$5.2 \times 10^{-6}/C$	815	640

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*Overview* *Thin-Film Technologies*

## Growth of thin films

Deposition Processes for Thin Films

- Primary Goal - High rate, good quality, low cost
- Vacuum Processes
  - r.f and d.c. magnetron sputtering
  - Sublimation (evaporation)
- Chemical Vapor Processes
  - LP CVD, PECVDE
- Atmospheric Pressure Processes
  - ED, CBD, Spray Deposition, Various Printing

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*Overview* *Thin-Film Technologies*

## Growth of thin films (Cont)

**Thin-Film PV Candidate Materials**

- III-V (InP, GaAs)
  - II-IV-V (ZnSnP, ZnGeAs)
- II-VI (CdTe)
  - I-II-VI ( $Cu_2S$ )
  - I-III-VI (CIS)
- Significant problems with III-V
  - Active grain boundaries?
  - Passivation of GB not successful
  - Best poly devices ~10%
- Better luck with II-VI
  - Benign grain boundaries
  - Tend to be columnar grains
  - Poly II-VI materials often better than crystal

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*Overview* *Thin-Film Technologies*

## Grain Boundaries

**Grain Boundaries**

- Regions of high defects
- Controlling factor of film
- Coherent twins (OK)
- Low-angle GB (Problem)
- High-angle GB (Bad)

TEM cross section view of a CdTe solar cell

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**Overview** **Thin-Film Technologies**

## Grain Boundaries (Cont)

Grain Boundaries (GBs)

- GBs can be regions of depletion, inversion, or accumulation
- Modification of GB
  - Neutralization by adding impurities
  - Capping with an insulator
  - Place GB in the junction
- In thin-film PV, we do not yet know how to control the influence of GB.
- Most GB optimization is experimentally determined.

Labels in diagram: Te covered surface, Cd(Te,S), CdTe, CdS, ITO

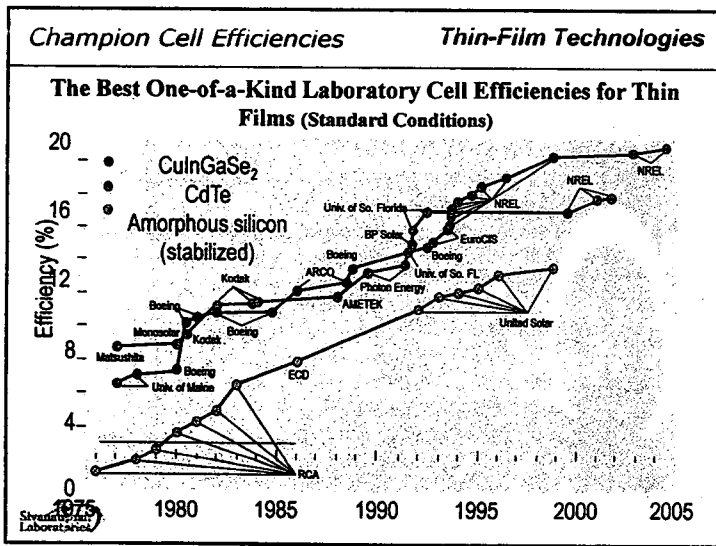
**Overview** **Thin-Film Technologies**

## Impact of Grains and Grain Boundaries on Device Performance

In General:

Recombination at GBs does not significantly limit current collection  
 High defect density at interface does not limit voltage (though high recombination current / low lifetime)

Reasons for this will be explained in following section



### Some CIGS-alloy, CdTe, & a-Si Laboratory Cells

	Area (cm <sup>2</sup> )	V <sub>oc</sub> (mV)	J <sub>sc</sub> (mA/cm <sup>2</sup> )	FF (%)	Eff* (%)	Comment
CIGSe	0.410	697	35.1	79.52	20.0	CIGSe/CdS, NREL, 3-Stage
CIGSe	0.402	670	35.1	78.78	18.5	CIGSe/ZnS, Nakada et. al.
CIGS	0.409	830	20.9	69.13	12.0	CIGS/CdS, FSEC
CIAS	-	621	36.0	75.50	16.9	CIAS/CdS, IEC, 1.15 eV
CdTe	1.03	845	25.9	75.51	16.7	CTO/ZTO/CdS/CdTe, NREL, CSS
CdTe	-	-	-	-	17.3	First Solar VTD ???
CdTe	0.814	814	23.25	73.25	14.3	SLG,FTO/TO/CdS/CdTe, EPIR, CSS
a-Si	-	-	-	72.25	12.1	

\*NREL Confirmed Efficiencies

**Champion Module Efficiencies Thin-Film Technologies**

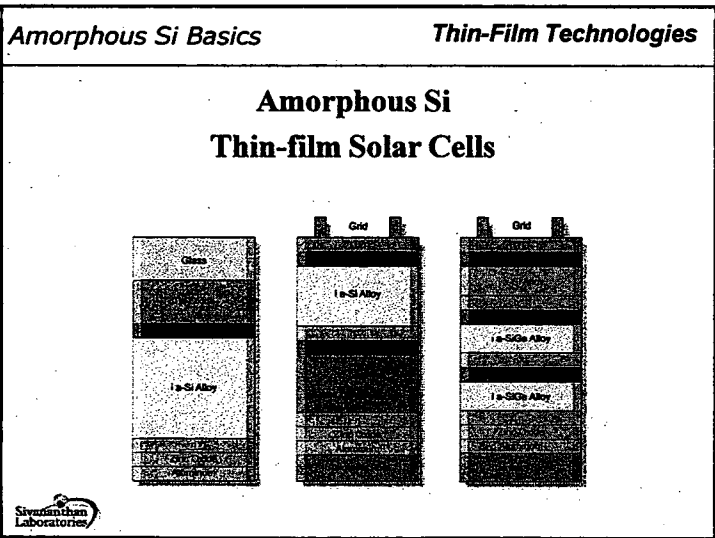
Company	Technology	Area (cm <sup>2</sup> )	Efficiency (%)	Power (W)	Date
Miasole	CIGS	9762	13.6-13.8		4/10
Global Solar	CIGS	8390	10.2*	88.9	8/02
First Solar	CdTe	6623	14.3*		8/08
Wurth Solar	CIGS	6500	13.0	84.6	6/04
United Solar	a-Si	4519	7.9*	35.7	6/97
Shell Solar	CIGSS	3626	12.8*	46.5	3/03
Showa Shell	CIGS	3459	13.5		8/02

\*Module Efficiencies Measured at NREL

**Comparing Thin Film Technologies Thin-Film Technologies**

**Comparison of Three Thin-Film PV Technologies Indicating Present Strengths of Each Technology**

Technology	Demonstrated Efficiency	Perceived Production Advantage	Perceived Materials Abundance/ Low Toxicity
a-Si			Strength
CdTe		Strength	
CIS	Strength		



**Amorphous Si Basics Thin-Film Technologies**

**Crystalline Si vs. a-Si vs. a-Si:H**

Crystalline Si is an indirect band gap semiconductor with  $E_g = 1.1 \text{ eV}$

Disordered Si (amorphous Si) changes nature of absorption  $E_g = 1.7 \text{ eV}$

a-Si without H (e.g., sputtered from Si) contains unsaturated dangling bonds

Defect density  $\sim 10^{19} \text{ cm}^{-3}$

Essentially useless for PV applications

H in a-Si (5-20%, from decomposition of  $\text{SiH}_4$ ) saturates dangling bonds

Defect density reduced to  $10^{15} - 10^{16} \text{ cm}^{-3}$

41-5

*Amorphous Si Basics* *Thin-Film Technologies*

### Plasma-Enhanced (PE)CVD

- Pressure 0.3 - 2 Torr
- Elect. gap 1 - 3 cm
- Sub. Temp. 150 - 300° C
- RF Power 5 - 25 mW/cm<sup>2</sup>
- H<sub>2</sub>:SiH<sub>4</sub> to get μc-Si formation ~ 30:1
- Dep. Rate ~3 Å/sec typical
- Also called Glow Discharge

Figure courtesy Brent Nelson, NREL

*Amorphous Si Basics* *Thin-Film Technologies*

### Doping and Simple Devices

Typical undoped a-Si:H is typically intrinsic or slightly n-type  
 Contains impurities (O, N, and C) at 10<sup>18</sup>-10<sup>19</sup> cm<sup>-3</sup>  
 Reduction of these impurities to 10<sup>15</sup> range does not improve devices

Luckily - Extrinsic doping just like crystalline or polycrystalline Si:  
 Boron (p-type) and Phosphorus (n-type)

Unfortunately - Doping decreases electrical quality (reduces carrier lifetime)  
 Cannot use doped layers for absorber layers  
 Use and intrinsic (i-layer) for high-performance devices

Dave Carlson patented n-i-p device 1972

*Amorphous Si Basics* *Thin-Film Technologies*

### Typical a-Si:H Solar Cell (Single-Junction)

- p-layer
- 80 - 200 Å
- wide bandgap (a-SiC:H or μc-Si:H)
- boron doped
- i-layer
- 2000 - 5000 Å
- 1.68 - 1.75 eV
- n-layer
- 200 - 400 Å
- phosphorous doped

Companies Making n-i-p a-Si single junction :  
 EPV, BP Solar (closed thin-film)

Figure courtesy Brent Nelson, NREL

*Amorphous Si Basics* *Thin-Film Technologies*

### Stability

1977 - Staebler and Wronski noted significant changes in optoelectronic properties of a-Si:H when material was exposed to light that were reversible on annealing at 150° C for a few hours. This is now known as the Staebler-Wronski effect (SWE)

Thinner i-layers reduce SWE, but this provides less light absorption

#### Understanding

It appears that the high electric field in thin i-layer reduces the SWE  
 SWE effect may be due to multiple causes  
 Work is still being done

*Amorphous Si Basics* *Thin-Film Technologies*


### a-Si:H Alloys and $\mu\text{-Si}$

**a-Si:H bandgap is changed by depositing alloys:**  
 Ge lowers  $E_g$ , C raises  $E_g$   
 a-Si:H = 1.72 eV,  
 5% Ge = 1.65 eV, 20% Ge = 1.45eV, 60% = 1.30 eV  
 20% C = 2.0 eV

a-SiC has been used for wide-gap top cell (1.72 eV), but proved unstable, now most devices use a-Si:H

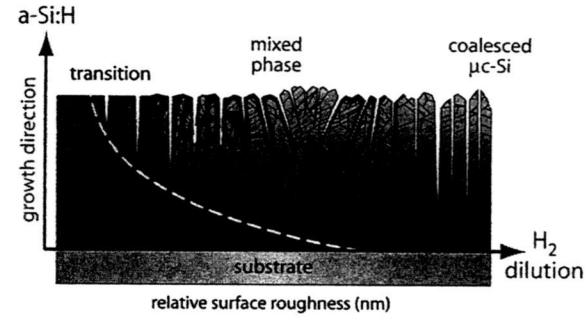
Quantum Efficiency decreases for wider bandgap (more Ge in a-Si:H)

$\mu\text{-Si}$ :H being developed as replacement for narrow bandgap a-SiGe:H (indirect bandgap ~1.3 eV)



*Amorphous Si Basics* *Thin-Film Technologies*

### Thin-Film Si Material Basics - a-Si:H Alloys and $\mu\text{-Si}$




relative surface roughness (nm)

crystallites  
  amorphous regions  
  voids  
  substrate

Figure courtesy Brent Nelson, NREL


*Amorphous Si Basics* *Thin-Film Technologies*



**200 nm**

TEM of Si:H Deposited with  $\text{H}_2/\text{SiH}_4=20$  on c-Si/SiO<sub>2</sub>

Figure courtesy Brent Nelson, NREL



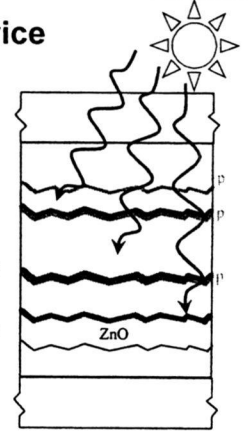
*Amorphous Si Basics* *Thin-Film Technologies*

### a-Si:H Multi-Junction Device

**Benefits of Multi-Junctions**

- Higher efficiencies
- Stable devices
- Thinner i-layers

**Companies Making nip a-Si triple junction :**  
UniSolar




$E_g > 1.72 \text{ eV}$

$1.60 \text{ \AA} E_g \text{ \AA } 1.65$

$1.40 \text{ \AA} E_g \text{ \AA } 1.45$

ZnO

Figure courtesy Brent Nelson, NREL



D1-7

*Amorphous Si Basics* *Thin-Film Technologies*

### Stability


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*Amorphous Si Basics* *Thin-Film Technologies*


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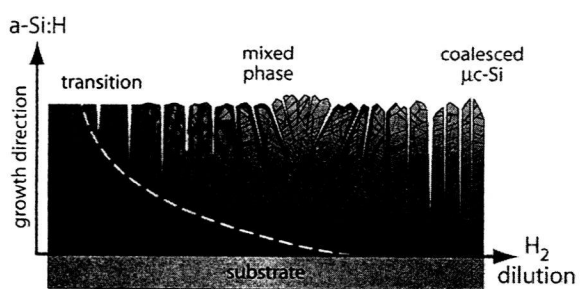
Quantum Efficiency decreases for wider bandgap (more Ge in a-Si:H)

μc-Si:H being developed as replacement for narrow bandgap a-SiGe:H (indirect bandgap ~1.3 eV)



*Amorphous Si Basics* *Thin-Film Technologies*


### Thin-Film Si Material Basics - a-Si:H Alloys and μm-Si



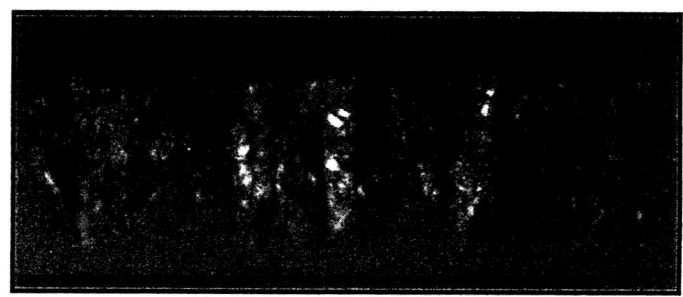
relative surface roughness (nm)

■ crystallites ■ amorphous regions ■ voids ■ substrate

Figure courtesy Brent Nelson, NREL




*Amorphous Si Basics* *Thin-Film Technologies*



200 nm

TEM of Si:H Deposited with  $H_2/SiH_4=20$  on c-Si/SiO<sub>2</sub>  
 Figure courtesy Brent Nelson, NREL



*Amorphous Si Basics* *Thin-Film Technologies*

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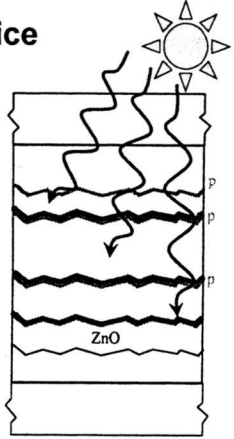



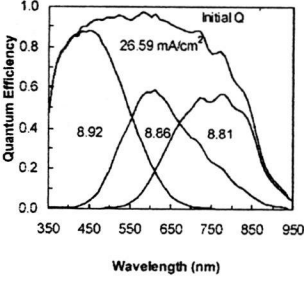
Figure courtesy Brent Nelson, NREL



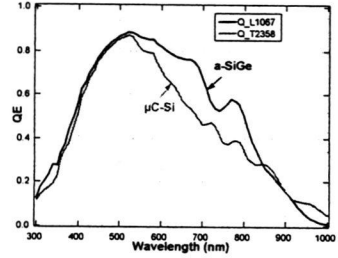
*Amorphous Si Basics* *Thin-Film Technologies*

### Thin-Film Si Material Basics - a-Si:H Alloys

Research is proceeding on improving the quality of the wide-gap alloys




UniSolar Triple-Junction Device. Number indicate current density from individual junctions



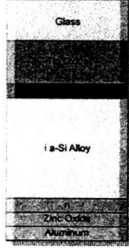


NREL Single-junction devices  
(Recent results suggest μm-Si as good as a-SiGe:H)


Figure courtesy Brent Nelson, NREL



*Amorphous Si Basics* *Thin-Film Technologies*

### Review Amorphous Si Thin-film Solar Cells (What Have We Learned?)




*CIGS Basics* *Thin-Film Technologies*

### CuInSe<sub>2</sub>-Alloy (CIGS) Thin-film Solar Cells

ZnO, ITO - 2500Å
CdS - 700Å
<b>CIGS</b> 1-2.5μm
Mo - 0.5-1μm
Glass, Metal Foil, Plastics

↑

**Process Direction**



**CIGS Basics** **Thin-Film Technologies**

## Chalcopyrites

Combines:  
Group (I) + Group (III) + Group (VI) Group IV  
(I)(III)(IV)<sub>2</sub> e.g., Si, a-Si

						Group II	Group VI	II-VI	
		B	C	N	O	e.g., CdTe			
		Al	Si	P	S	Group I	Group III	Group VI	
Cu	Zn	Ga	Ge	As	Se	e.g., CuInGaSe <sub>2</sub>			
Ag	Cd	In	Sn	Sb	Te	Group I	Group II	Group IV	Group VI
							<b>Kesterites</b>		
							e.g., Cu <sub>2</sub> ZnSnSe <sub>4</sub>		

Sivaraman Laboratories

**CIGS Basics** **Thin-Film Technologies**

## CIGS Phase Diagram

By counting atoms, one notes single phase CIS (CuInSe<sub>2</sub>) should form at about 25% Cu.

Cu-poor CIS is called alpha-phase material.

Alpha-phase CIS is preferred

- p-type
- Bandgap of ~0.8 eV (1200 nm)
- Higher lifetime

Often, must deposit non-alpha phase and "process into" alpha phase

δ: sphalerite  
 α: chalcopyrite  
 β: "P" chalcopyrite

Phase diagram from T. Haszboom et al. Inst. Phys. Conf. Ser. No. 152, p. 249.

Sivaraman Laboratories

02-1

**CIGS Basics** **Thin-Film Technologies**

### Thin Film CIGS Solar Cells

ZnO, ITO 2500 Å  
CdS 700 Å

CIGS  
1-2.5 μm

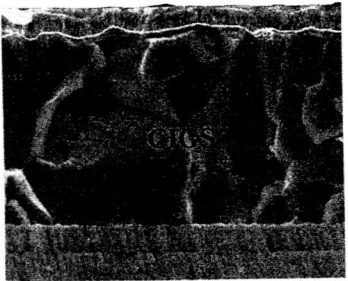
Mo 0.5-1 μm

Glass, Metal,  
Foil, or Plastics

n-type ZnO

p-type CIGS

Molybdenum  
Back electrode



2 μm

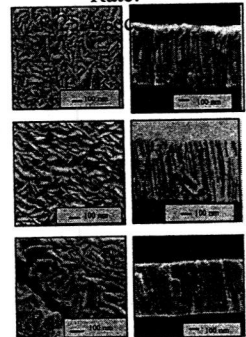
$\eta = 20.0\%$  (NREL)

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**CIGS Basics** **Thin-Film Technologies**

### Mo Back Contact Processing

Rate:



5 mTorr

8 mTorr

12 mTorr

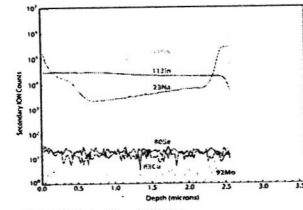
Pressure

5 mTorr

8 mTorr

12 mTorr

ZnO, ITO - 2500Å
CdS - 700Å
<b>CIGS - 1-2.5μm</b>
<b>Mo - 0.5-1μm</b>
Glass, Metal Foil, Plastics



H. Alkhami Thesis  
Source: R. Noufi and K. Zweibel, Proc. 4th WCPEC, Waikoloa, Hawaii, 5/2006.

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**CIGS Basics** **Thin-Film Technologies**

### Deposition Methods

Evaporation of the Elements

Vacuum

---

Sputtering of the Elements

Vacuum

---

Nanotechnology/Nano-particles-(Inks)

Printing

---

CVD-based (lab, R&D)

Low Vacuum

### CIGS Formation Pathways

1a. Cu + In + Ga Cu:In:Ga intermetallic

---

1b. Cu:In:Ga intermetallic + H<sub>2</sub>Se (or Se) Cu(In,Ga)Se<sub>2</sub>

2. Cu<sub>2</sub>Se + (In,Ga)<sub>2</sub>Se<sub>3</sub> Cu(In,Ga)Se<sub>2</sub>

---

Cu + In + Ga + Se Cu(In,Ga)Se<sub>2</sub>

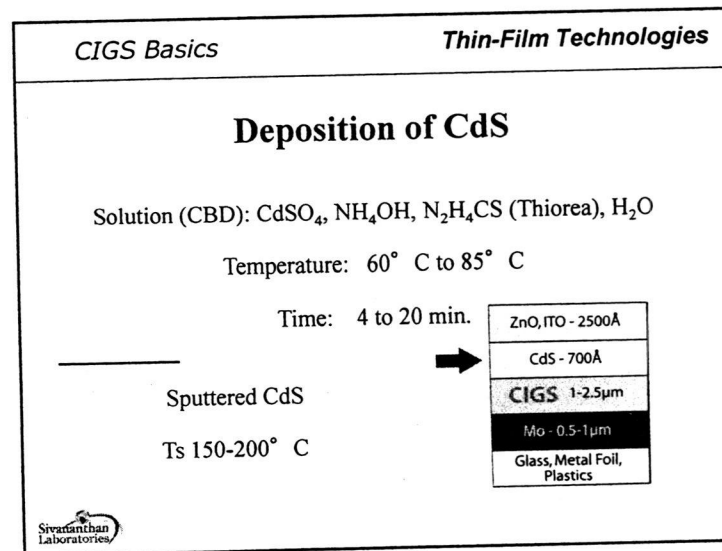
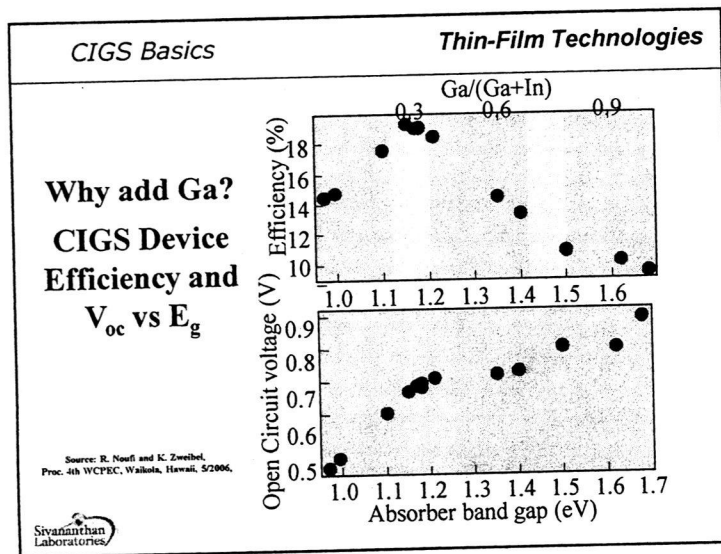
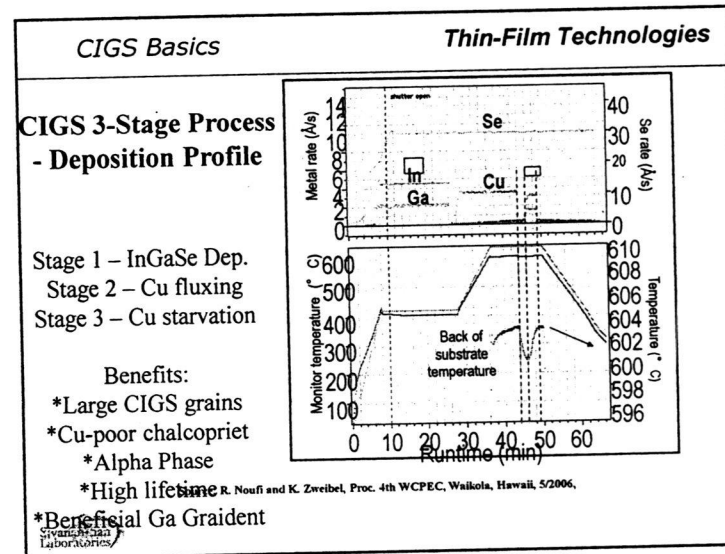
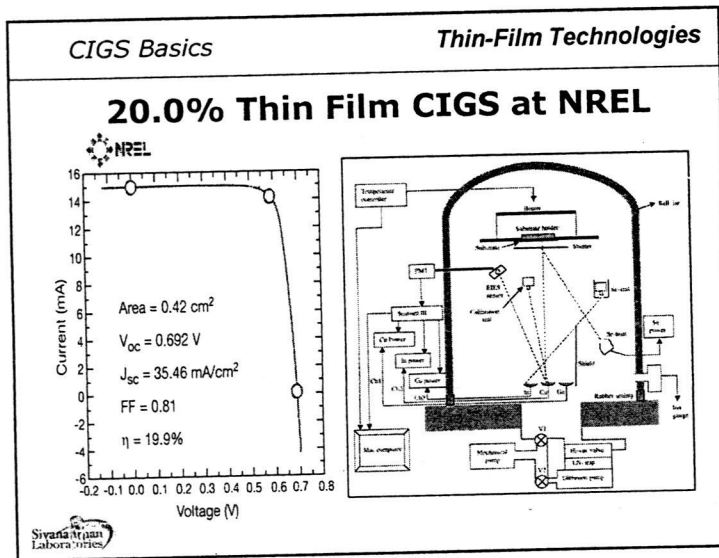
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**CIGS Basics** **Thin-Film Technologies**

### Thin Film CIGS Technology

Company	Substrate	Back Contact	Process	Window Layer
Solar Frontier	Glass	Mo	Sputter/Selenize/Sulfurize	ZnO
Global Solar	Steel	Mo	Co-Evaporation	ITO
MiaSole	Steel	Mo	Sputter	ZnO
Wurth Solar	Glass	Mo	Co-Evaporation	ZnO
Avancis	Glass	Mo	Sputter/RTP	ZnO
Daystar Tech	Glass	Mo	Sputter	ZnO
Honda	Glass	Mo	Sputter/Selenize	ZnO
Ascent Solar	Polymer	Mo	Co-Evaporation	ZnO
ISEC	Glass/Flex	Mo	Ink/Selenization	ZnO
Nanosolar	Flexible	Mo	Print/RTP	ZnO
Heliovolt	Glass/Flex	Mo	Fast	ZnO
SolarPower	Steel	Mo	Electrodeposition/RTP	ZnO

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1-37

## CdTe Thin Film Solar Cells

## CdTe

### Advantages:

- Ideal band gap - 1.5 eV, direct gap semiconductor, requires only 2  $\mu\text{m}$  thickness to absorb most of the spectrum.
- Simple binary system, can be prepared by many techniques. Properties favor formation of single phase material.
- Exists in both n and p type.
- CdS works as a good hetero-junction partner.

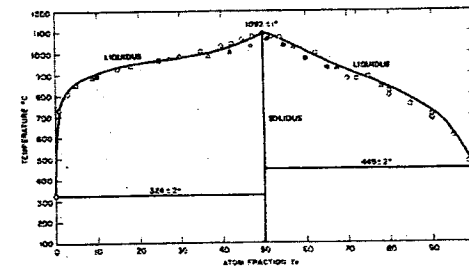
### Disadvantages:

- Difficult to dope p-type. Properties controlled by native defects in the material. In polycrystalline material, extrinsic dopants accumulate at the grain boundaries.
- Ohmic Contact - CdTe has high work function 5.8 eV. No suitable metals for forming ohmic contacts. Need to form intermediate layer to get tunneling contact.
- This requires use of inverted structure where CdTe contact formation is the last step.

### CdTe Basics

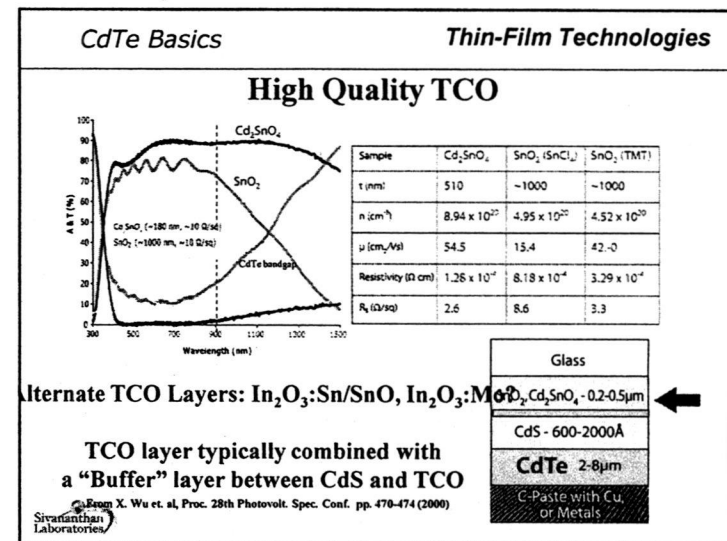
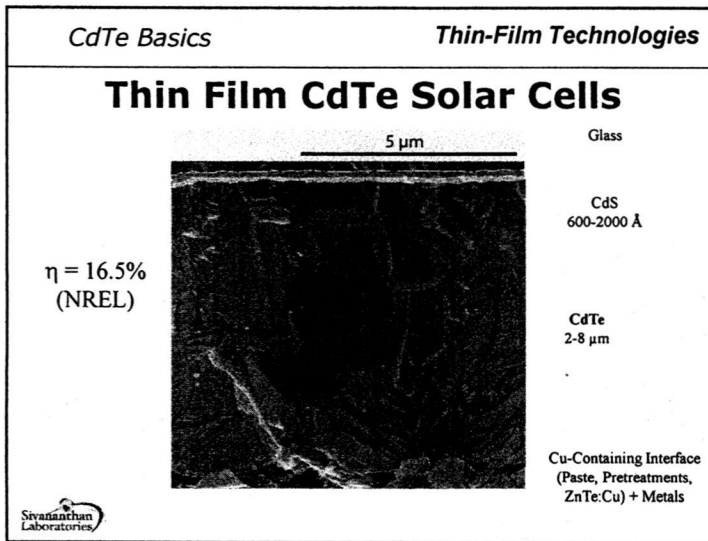
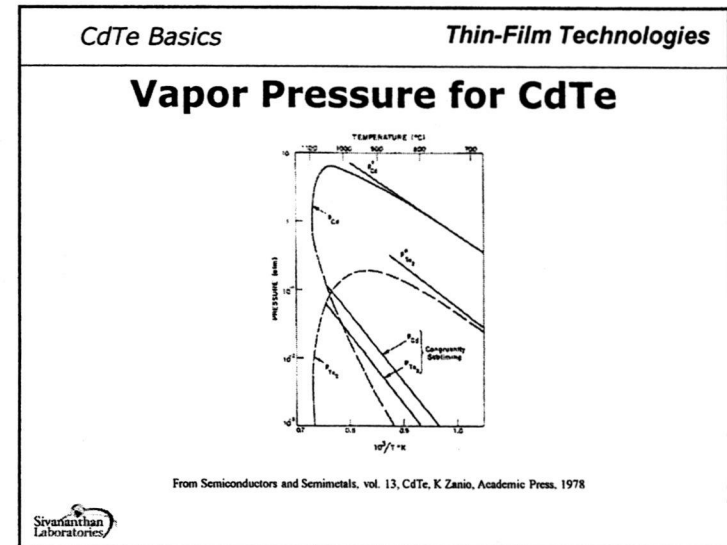
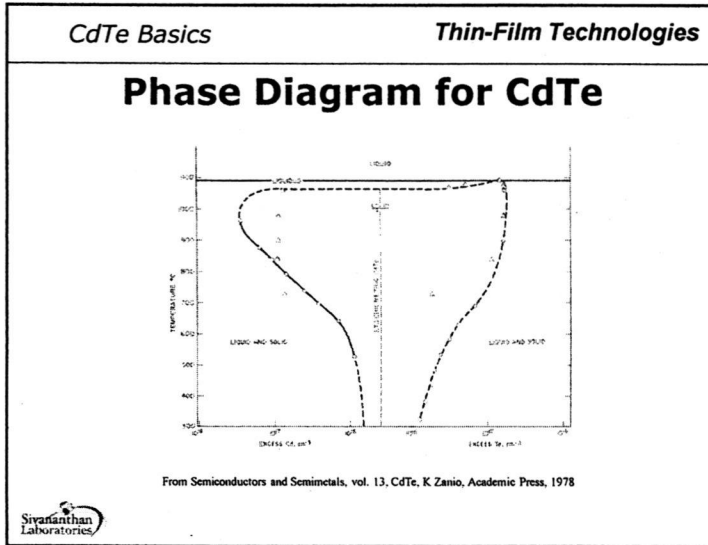
### Thin-Film Technologies

## Phase Diagram for CdTe



From Semiconductors and Semimetals, vol. 13, CdTe, K Zanio, Academic Press, 1978

D3-2



45-3

### Atomic force micrographs of SnO<sub>2</sub> and Cd<sub>2</sub>SnO<sub>4</sub>

- The areas examined were 1x1 μm
- Typical SnO<sub>2</sub>, r.m.s. roughness was ±126 Å
- The Cd<sub>2</sub>SnO<sub>4</sub> roughness was ±32 Å
- This is important for CdTe solar cells

9

**CdTe Basics**
**Thin-Film Technologies**

#### Buffer Layer

Glass
SnO <sub>2</sub> /Cd <sub>2</sub> SnO <sub>4</sub> - 0.2-0.5μm
CdS - 600-2000Å
<b>CdTe - 2-8μm</b>
C-Paste with Cu or Metals

See also: X. Wu and J. Zhou Proc. 19th European PV Solar Energy Conf. 2004, pp. 1721-1724

**TCO layer typically combined with a "Buffer Layer" (BL) between CdS and TCO**

BL Attributes: Allows thinner CdS layers, Reduces pinholes, Reduces Problems with Over-etching, Allow Hotter/longer CdCl<sub>2</sub> treatments

Ref. X. Wu, et al., "Interdiffusion of CdS and Zn-SnO<sub>2</sub> Layers and its Application in CdS/CdTe BL Materials Underpin Se<sub>2</sub>S<sub>3</sub> Film, O<sub>2</sub> and Zn<sub>1-x</sub>Sn<sub>x</sub>O<sub>2</sub> related alloys

**CdTe Basics**
**Thin-Film Technologies**

**CdTe PV Module (~850 nm Bandgap)**

Loss of ~1.5 mA/cm<sup>2</sup> for Commercial Glass

Loss of ~1.5 mA/cm<sup>2</sup> for Commercial TCO

Model Parameters:  
 Mobility ~30 cm<sup>2</sup>/V-sec  
 Carrier Concentration ~7x10<sup>19</sup> cm<sup>-3</sup>

**CdTe Basics**
**Thin-Film Technologies**

Sputtered CdS:O

Bandgap increases as Oxygen is added

#### CdS Layer

Glass
SnO <sub>2</sub> /Cd <sub>2</sub> SnO <sub>4</sub> - 0.2-0.5μm
CdS - 600-2000Å
<b>CdTe - 2-8μm</b>
C-Paste with Cu or Metals

X. Wu et al. 2004 PVSC, pp. 551-554

**Solution Growth**

Thickness: 300 nm (Industry) , 50-100 nm (Research)

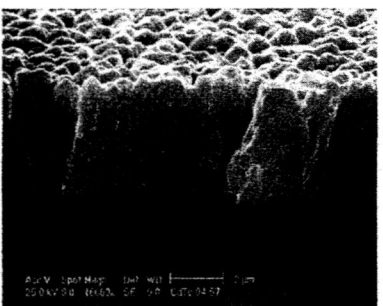
- Solution Growth (CBD) - CdSO<sub>4</sub>, NH<sub>4</sub>OH, N<sub>2</sub>H<sub>4</sub>CS (Thiorea), H<sub>2</sub>O
- Temperature - 60° C to 85° C, Time - 15 to 30 min.

Other Methods/Materials: CSS, Gas-Phase Transport, Sputtering, CdS:O (nanocrystalline), CdS:In (n-type doped)

23-4

**CdTe Basics** **Thin-Film Technologies**

### CdTe Layer



Glass
SnO <sub>2</sub> /Cd <sub>2</sub> SnO <sub>4</sub> - 0.2-0.5µm
CdS - 600-2000Å
<b>CdTe - 2-8µm</b>
C-Paste with Cu or Metals

Two Categories:  
 Low Dep. Temp. (<425°)  
 • Small Grain  
 • N-type  
 • Oriented with stress  
 High Dep. Temp. (>500°)  
 Large grain

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**CdTe Basics** **Thin-Film Technologies**

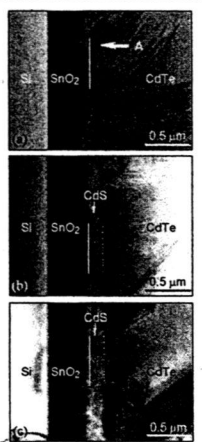
### CdCl<sub>2</sub> heat treatment

- Most crucial step in the fabrication of the cell. Can be called "Equalizer step". Improves device performance dramatically for low temp. films and significantly for high temp. films.
- Treatment with solution CdCl<sub>2</sub> (dip in CdCl<sub>2</sub> methanol) or vapor CdCl<sub>2</sub>. Treatment temp. of around 400° C
- In electro-deposition and spray technique, CdCl<sub>2</sub> can be included in the deposition process followed by HT anneal.
- CdCl<sub>2</sub> heat treatment promotes recrystallization and grain growth in CdTe and CdS deposited at lower temperature. It promotes interdiffusion between CdS and CdTe. It also improves the electronic properties of the material and device performance. CdCl<sub>2</sub> is generally considered fluxing agent that decreases the required treatment temperature at which physical changes occur.

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**CdTe Basics** **Thin-Film Technologies**

Transmission Electron Microscopy (TEM)



CSS CdS (no treatments)  
**Large** consumption of CdS layer

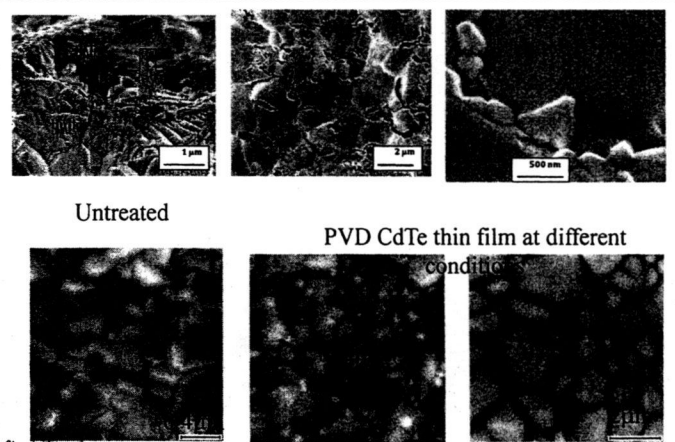
CSS CdS (oxygen annealed)  
 Much **less** CdS consumption

"control" structure  
 CBD CdS + CSS CdTe (1 torr oxygen)  
**Little** CdS consumption

As-grown CBD CdS contains oxygen (10-12 at.%). CdS is not readily consumed during CdTe growth. CSS CdS contains less oxygen (2-3 at.%). CdS consumption is greater, but can be

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**CdTe Basics** **Thin-Film Technologies**

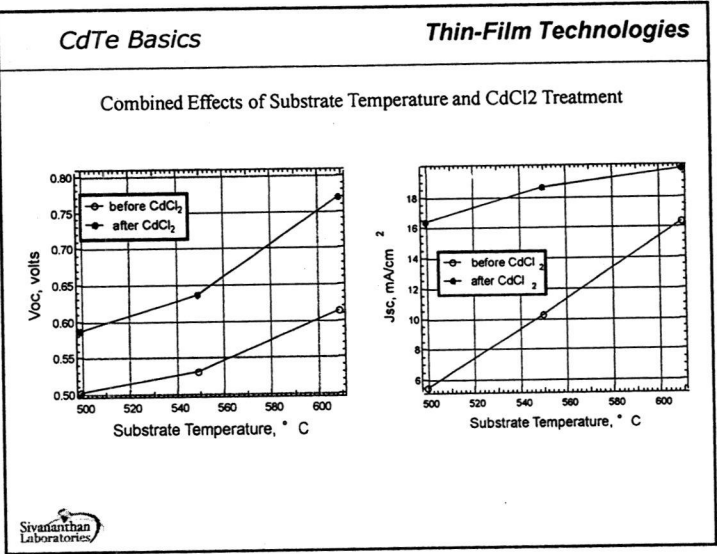
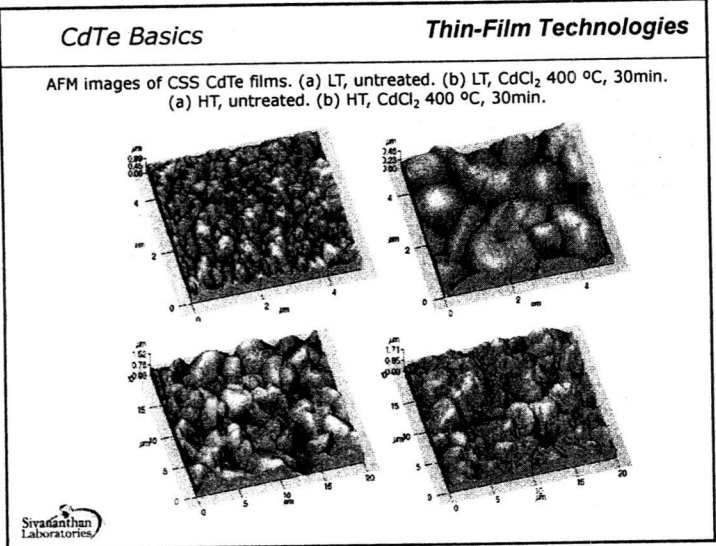


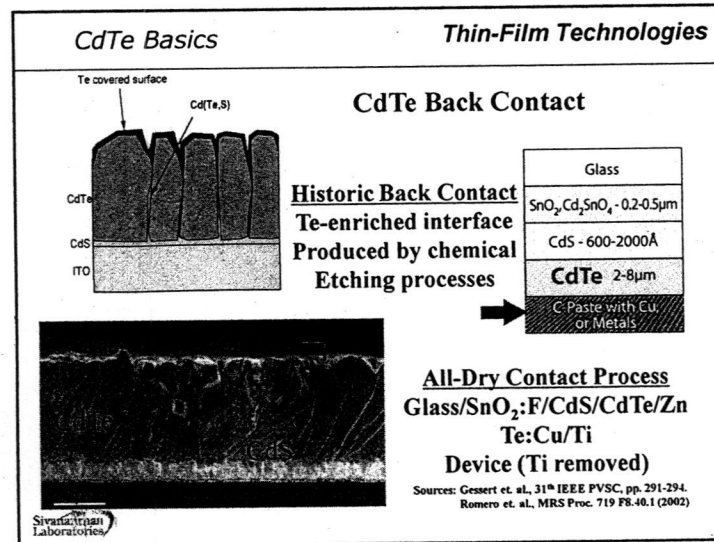
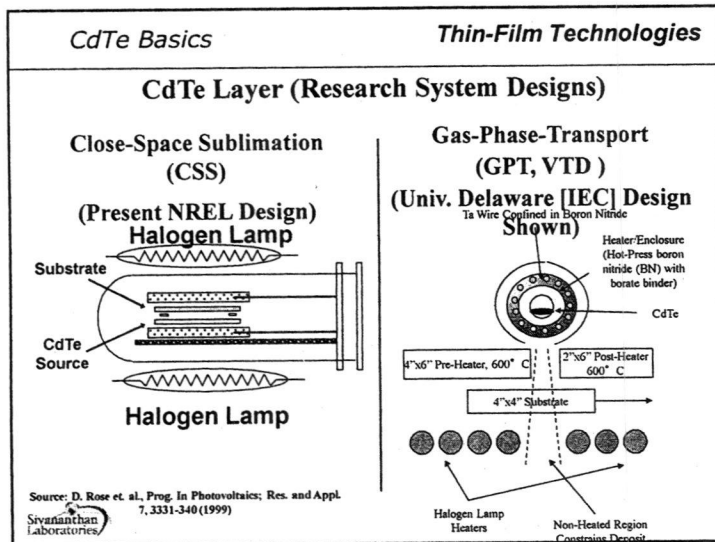
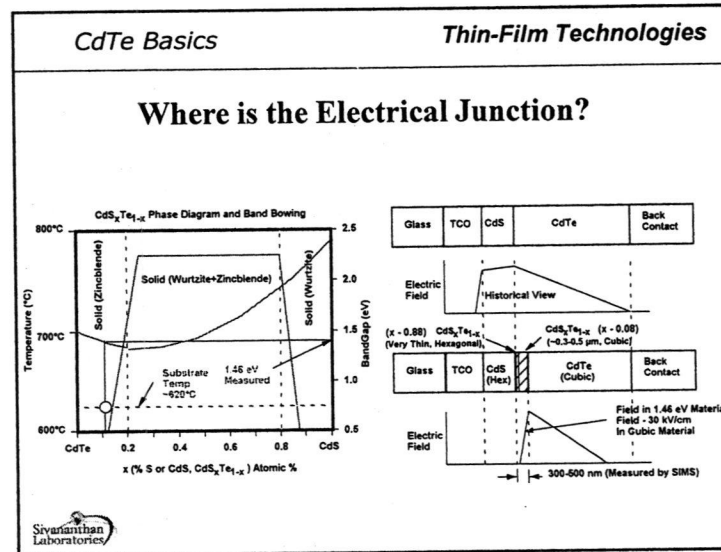
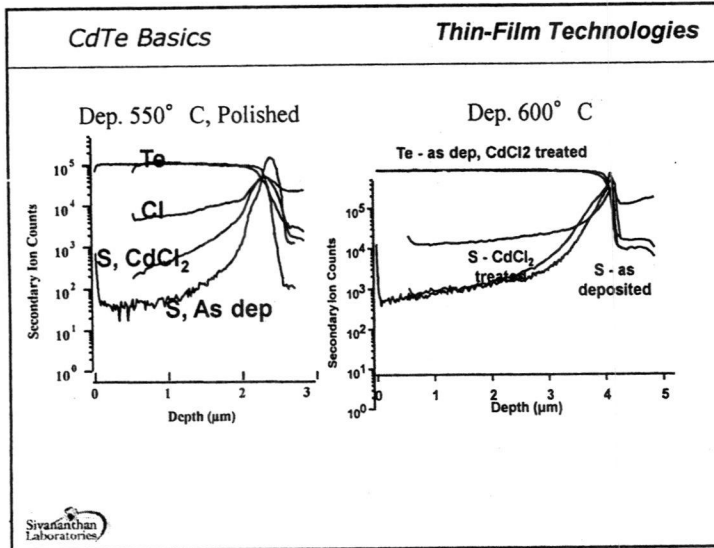
Untreated

PVD CdTe thin film at different conditions

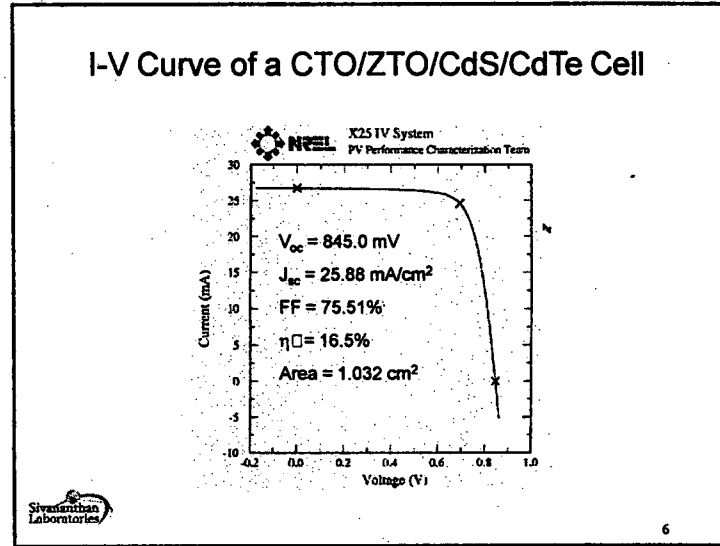
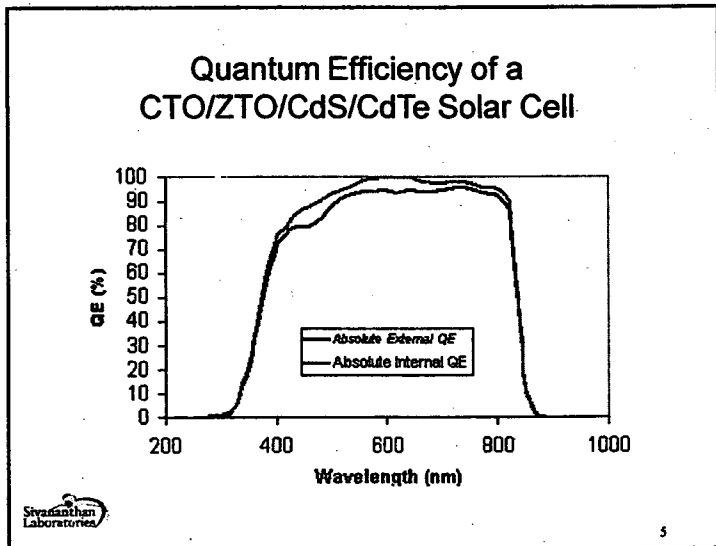
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D3-5





AA-2



### Cell QE losses for 2 cases

	Thick CdS (250 nm) with commercial SnO <sub>2</sub>	Thin CdS (80 nm) with CTO/ZTO
TCO	4.4 mA/cm <sup>2</sup>	0.74 mA/cm <sup>2</sup>
Reflection	1.7 mA/cm <sup>2</sup>	1.19 mA/cm <sup>2</sup>
CdS	5.8 mA/cm <sup>2</sup>	1.4 mA/cm <sup>2</sup>
Deep penetration	1.1 mA/cm <sup>2</sup>	
J <sub>sc</sub>	17.6 mA/cm <sup>2</sup>	25.65 mA/cm <sup>2</sup>
J <sub>max</sub>	30.5 mA/cm <sup>2</sup>	29.5 mA/cm <sup>2</sup>
Losses	12.9 mA/cm <sup>2</sup>	3.5 mA/cm <sup>2</sup>

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### Efficiency loss mechanisms

Comparing CdTe devices with GaAs which has a similar bandgap:

- Difference in J<sub>sc</sub> is minimal, the losses are well understood
- Loss in Voc is ~ 200 mV. Due to a large diode quality factor (1 vs 1.9), the difference at V<sub>mp</sub> is even more ~ 300 mV. Due to additional recombination losses, excess forward current for CdTe 2 orders of magnitude higher.
- Of the 9.2 % efficiency difference, most of the losses attributed to poly-crystallinity.
- In addition to the increased recombination, poly-crystallinity also results into non-uniformity resulting in further performance loss.

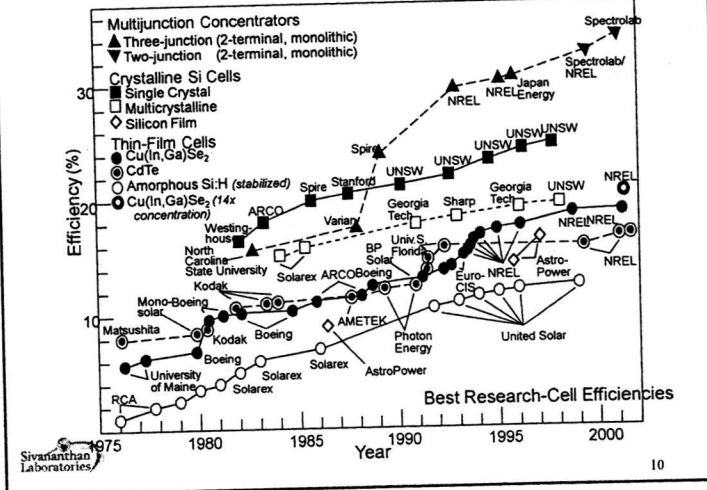
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### CdTe Industry (First Solar LLC)



Sivaraman  
Laboratories

### Present Status



DB-1

## Electrical Properties and Module Design

Ramesh G. Dhere  
Strategic Advisor, Sivananthan Laboratories,  
Bollingbrook, Illinois, USA



## Device Analysis

Key device parameters for device performance

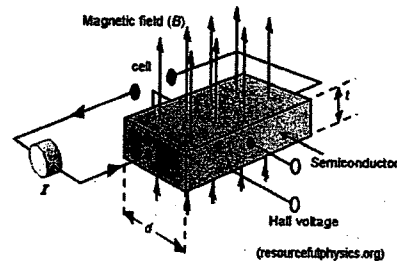
- Diffusion length – function of mobility ( $\mu$ ) and lifetime of the carriers. determines the collection efficiency of carriers, determines  $J_{sc}$ .
- Carrier density determines the resistivity and position of Fermi level of the semiconductor. Relevant for FF and  $V_{oc}$ .
- Lifetime ( $\tau$ ) of minority carriers is affected by the recombination which determines the dark current ( $J_0$ ) of the diode.  $V_{oc}$  is function of the ratio of  $J_{sc}/J_0$ .



2

## THE HALL EFFECT

- Lorentz Force:
- $F = q[E + (v \times B)]$



- Hall voltage is produced by charge accumulation on sidewalls
- Charge accumulation balances Lorentz Force
- Charge accumulation increases resistance



## THE HALL EFFECT: SEMICONDUCTORS

What we can learn

- Sign of charge carrier
- Charge carrier density
- Charge carrier mobility
- Temperature dependence of mobility gives the indication of dominant scattering mechanism (important for thin film devices to optimize properties)



### HALL VOLTAGE

For simple conductors

$$V_H = \frac{-IB}{ned} = R_H \frac{IB}{d}$$

Where n = carrier density, d = conductor length

- $R_H$  is known as the Hall coefficient
- $V_H \propto B \rightarrow$  Useful for measuring B-Fields



### HALL COEFFICIENT

• Semiconductors have two charge carriers

$$R_H = \frac{-n\mu_c^2 + p\mu_h^2}{e(n\mu_c^2 + p\mu_h^2)^2}$$

• However, for large magnetic fields

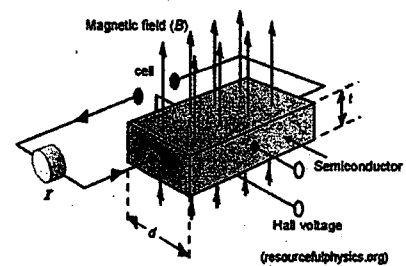
$$R_H = \frac{1}{(p-n)e}$$

• Enables us to determine the carrier density



### THE HALL EFFECT

- Lorentz Force:
- $F = q[E + (v \times B)]$



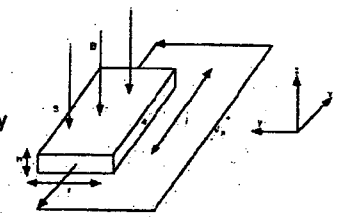
- Hall voltage is produced by charge accumulation on sidewalls
- Charge accumulation balances Lorentz Force
- Charge accumulation increases resistance



### THE HALL EFFECT: SEMICONDUCTORS

- Why Semiconductors?
  - Ideal number of charge carriers
  - Charge carriers increase with temperature

- What we can learn
  - Sign of charge carrier
  - Charge carrier density
  - Charge carrier mobility



## HALL VOLTAGE

For simple conductors

$$V_H = \frac{-IB}{ned} = R_H \frac{IB}{d}$$

Where  $n$  = carrier density,  $d$  = conductor length

- $R_H$  is known as the Hall coefficient
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## HALL COEFFICIENT

- Semiconductors have two charge carriers

$$R_H = \frac{-n\mu_e^2 + p\mu_h^2}{e(n\mu_e^2 + p\mu_h^2)^2}$$

- However, for large magnetic fields

$$R_H = \frac{1}{(p-n)e}$$

- Enables us to determine the carrier density
- Combine with  $\sigma = ne\mu$  to determine  $n$  and  $\mu$



## Temperature Dependence

- ☼ Temperature dependence of carrier mobility  $\mu(T)$  dependent on the dominant scattering mechanism, thus *elastic scattering* with change in energy on scattering  $kT$  described in terms of the average relaxation time between scattering events  $\langle \tau_r(E) \rangle$  given by

$$\mu(T) = \frac{q\langle \tau_r(E) \rangle}{m_{cond}^*}$$

where  $m_{cond}^*$  is the conductivity effective mass.



## Elastic Scattering

- Most important types of elastic scattering in semiconductors by acoustic lattice waves or acoustic phonons for which  $\tau_r(E) \propto E^{-1/2}$  and the acoustic mobility proportional to  $T^{-3/2}$  and by charged impurity scattering for which  $\tau_r(E) \propto E^{3/2}$  and the impurity mobility proportional to  $T^{+3/2}/N_i$ , where  $N_i$  the charged impurity density.

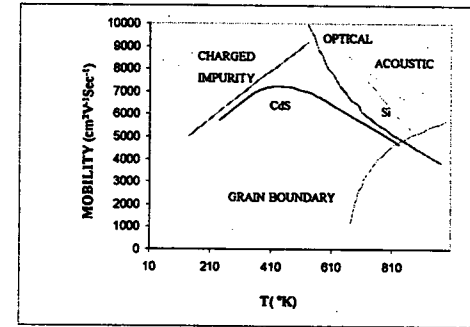


### Grain Boundary Scattering

- In polycrystalline material, grain boundary potentials may influence overall mobility, introducing an apparent increase in overall mobility with temperature.
- The temperature dependence of mobility summarized in following figure.



### Mobility Variation



### Total Mobility

- ⊗ Several modes always present and the total mobility obtained by the addition of reciprocals,

$$\frac{1}{\mu} = \frac{1}{\mu_c} + \frac{1}{\mu_i} + \frac{1}{\mu_a}$$

- ⊗ The temperature dependence for one-carrier conductivity  $\sigma_n$  of an n-type material given by

$$\sigma_n = qN_c \mu_n(T) e^{-\frac{(E_c - E_F)}{kT}}$$

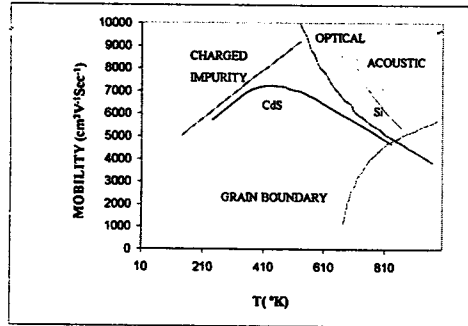


### Arrhenius Conductivity Plot

- A straight-line plot of  $\ln \sigma_n$  versus  $1/T$  with a slope of  $-(E_c - E_F)/kT$  only if all other temperature dependences cancel out such as in the simplest case of scattering of electrons by packets acoustic lattice wave or acoustic phonons for which the acoustic mobility proportional to  $T^{-3/2}$  which just cancels the temperature dependence of  $N_c$ .

DB 5

## Mobility Variation

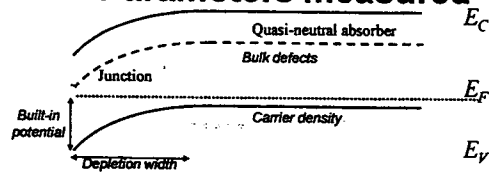


## Temperature Dependences

- In general, essential to measure separately the temperature dependences of charge carrier density and mobility, e.g. measurement of Hall effect as a function of temperature and then plot  $\ln(n_0 T^{-3/2})$  versus  $1/T$  to get a straight line slope.

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## Parameters measured



- Main junction:** depletion width  $W$ , carrier density profile  $N_a(W)$ , built-in voltage  $V_{bi}$
  - Neutral absorber:** bulk defects (density, energy, capture cross-section)
- | Measurands  | Techniques                               |
|---|--|
| AC response (depletion capacitance due to space charge and defect trapping) | Capacitance-voltage profiling (CV)       |
| • $C(V,dc)$   | Admittance spectroscopy (AS)             |
| • $C(\omega, T)$  | Drive-level capacitance profiling (DLCP) |
| • $C(V,ac)$   |  |
| Transient response (carrier population recovery from non-equilibrium state) |  |
| • Transient $C(t, T)$   | Deep-level transient spectroscopy (DLTS) |

## Capacitance-voltage profiling

- Principles**
  - Measures bias dependence of depletion capacitance,  $C(V_{dc})$ , to observe change of depletion region due to voltage bias.
  - Ideally applicable to single one-sided junction
  - Extracts depth profile of free carrier (or doping) concentration:  $N_a$  vs  $W$
  - Extracts built-in voltage  $V_{bi}$
- Special non-ideal cases:**
  - Multi-junction situation
  - Carrier freeze-out
  - Hysteresis

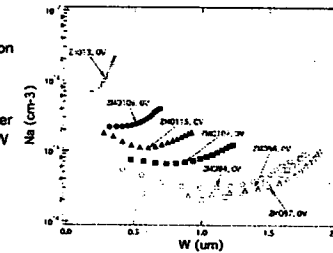


Fig. Carrier concentration  $N_a$  vs depletion width  $W$  are sensitive indicator of growth condition and device architecture. Data from a series of CIGS solar cells with different ZnMgO window layer.

\*\*These limitations are also opportunities of obtaining new understanding via development of new techniques and models.

DR-61

### Admittance spectroscopy

**Principles:**

- Measures the frequency and temperature dependence of depletion capacitance,  $C(f, T)$ , under reverse bias to observe the thermal activation of trapping-detrapping behavior.
- Obtains bulk defect properties (energy, capture cross-section, density of states)
  - Also obtains interface defects
- Measures diffusion capacitance under forward bias: obtains minority carrier lifetime

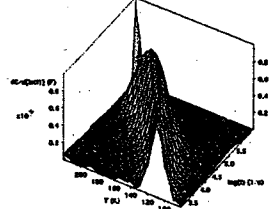


Fig. 1 Differential capacitance  $dC/df$  vs  $(T, f)$ . Data from a CIGS solar cell.

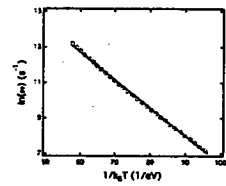


Fig. 2 Arrhenius plot to extract energy and capture cross-section.

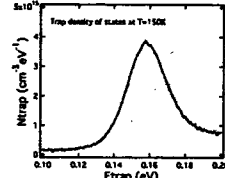


Fig. 3 Defect density of states.

### Deep level transient spectroscopy

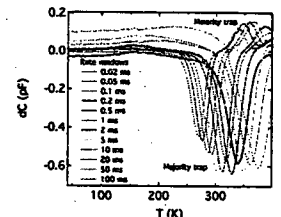


Fig. 1 DLTS raw signal vs T at various rate windows. Data from a GaAsN cell.

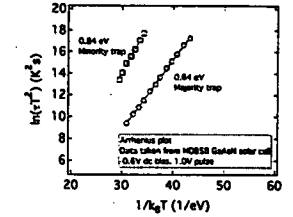
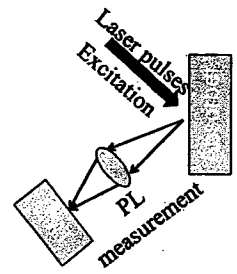
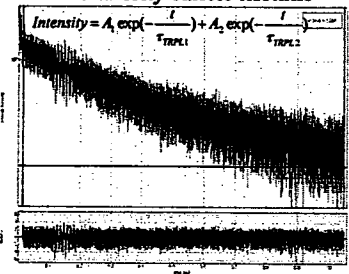
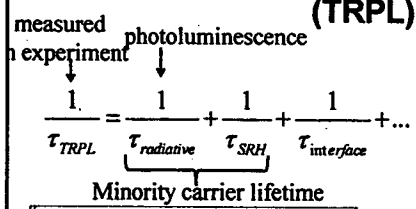


Fig. 2 Arrhenius plot to extract trap characteristics.

**Principles**

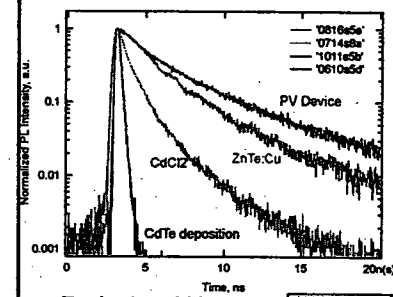
- Measures the time and temperature dependent recovery of capacitance transient,  $C(t, T)$ , due to carrier de-trapping after perturbation by a bias voltage pulse
- Obtains defect properties (energy, capture cross-section, density)
  - Obtains type of trapping (minority vs majority carrier traps)
    - Complementary to AS
- Applicable to transient ion drift study

### Time-Resolved Photoluminescence (TRPL)



Measure radiative recombination  
All recombination pathways contribute to decay rate  $(\tau_{TRPL})^{-1}$

### CdS/CdTe: defect reduction is monitored by rapid contactless measurement at RT



2-exponential decay model  
Longer lifetime means fewer recombination centers  
Increase in  $\tau_1$  and  $\tau_2$  during device fabrication  
No other contactless analysis method has such sensitivity

Excitation: 800 nm  
0.3 ps pulses  
2 nJ/pulse  
Measurement: 840 nm

	to absorber improvement	
deposition	1	0.087
CdCl <sub>2</sub>	0.86	Data interpretation is difficult
ZnTe:Cu	0.76	4.23